



DIM.	MIN.	TYP.	MAX.
* A	6.40		6.60
* B	4.30		4.50
C	-----		1.20
E	6.20		6.60
F		5.85	
H	0.05		0.15
J	0.17		0.30
L	0.45		0.75
P		0.65	
T	0.08		0.20
X	0°		8°
Y		12°	

NOTE :

\* A & B are reference data and do not include mold deflash or protrusions.

All dimensions in mm  
Angles are in degrees



**CML Microcircuits**

COMMUNICATION SEMICONDUCTORS

TITLE <b>20-pin TSSOP Package</b>	DRAWING No. <b>E3</b>	
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